Specifications

Insulation Resistance: Withstanding Voltage: Max. Working Current: Max. Working Voltage:

Contact Resistance: Operating Temp.Range: -55°C ~ +125°C Capacitance: Self Inductance: Mating Cycles:

 $10.000 M\Omega$ min. at 500V rms 500V rms 1A 100V rms / 150V DC for \ge 1.27mm pitch 50V rms / 60V DC for 1.00mm pitch $10m\Omega$ max. at 100mA/20mVmax. 1pF max. 2nH

Materials and Finish

Insulator: Contacts (stamped): Sleeves (machined): Adapter Pins (machined): Brass, Gold over Nickel

Laminated glass-epoxy FR 4, (UL94V-0) Beryllium Copper, clip Gold over Nickel Brass, Tin Lead over Nickel

Features

C The best way to make BGA plugable on PCB without layout design change

100 times

- The socket and PCB adapter provide a high density and low profile board interconnect system
- Minimum order quantity is 3 pieces per item



Part Number for Socket (Details)

91 - 256 * 16 *** *** **YED514** _ Series No.(socket) **Contact Plating:** Gold (0.25µm) over Tin Pin Count (variable pin choice) Pitch: K = 1.00 N = 1.50 M = 1.27 L = 2.54Grid Size: e.g. 16 = 16 x 16 Design Number Variation in case of identical Grid and Pin Count (Internal Use)

148 = for 1.27, 1.50, 2.54mm pitch 159 = for 1.00mm pitch

Part Number for Carrier (Details)

YED550 - 10 - 256 * 16 *** ***
Series No.(carrier) YED550 or YED558
Contact Plating: Gold (0.25µm) over Tin
Pin Count (variable pin choice)
Pitch: $K = 1.00$ $N = 1.50$ M = 1.27 $L = 2.54$
Grid Size: e.g. 16 = 16 x 16
Design Number Variation in case of identical Grid and Pin Count (Internal Use)
166 = YED550 Series with 1.27, 1.50, 2.54mm pitch

102 = YED558 Series with 1.00mm pitch

View of Carrier, Socket and IC

This Socket / Carrier system for BGA devices was designed for high pin count packages and a direct SMT assembly on the PCB.

The system consists of two parts:

The socket

- a standard type PGA socket with female contacts for soldering or SMT connection. The carrier

- -with metal pads on top side for SMT soldering of the BGA component and the other
- side male contacts to plug into the socket.

Contacts are arranged in grid patterns with a pitch of 1.00, 1.27, 1.50 or 2.54mm. Any Pin Count and Pin Layout within the customers defined grid size





